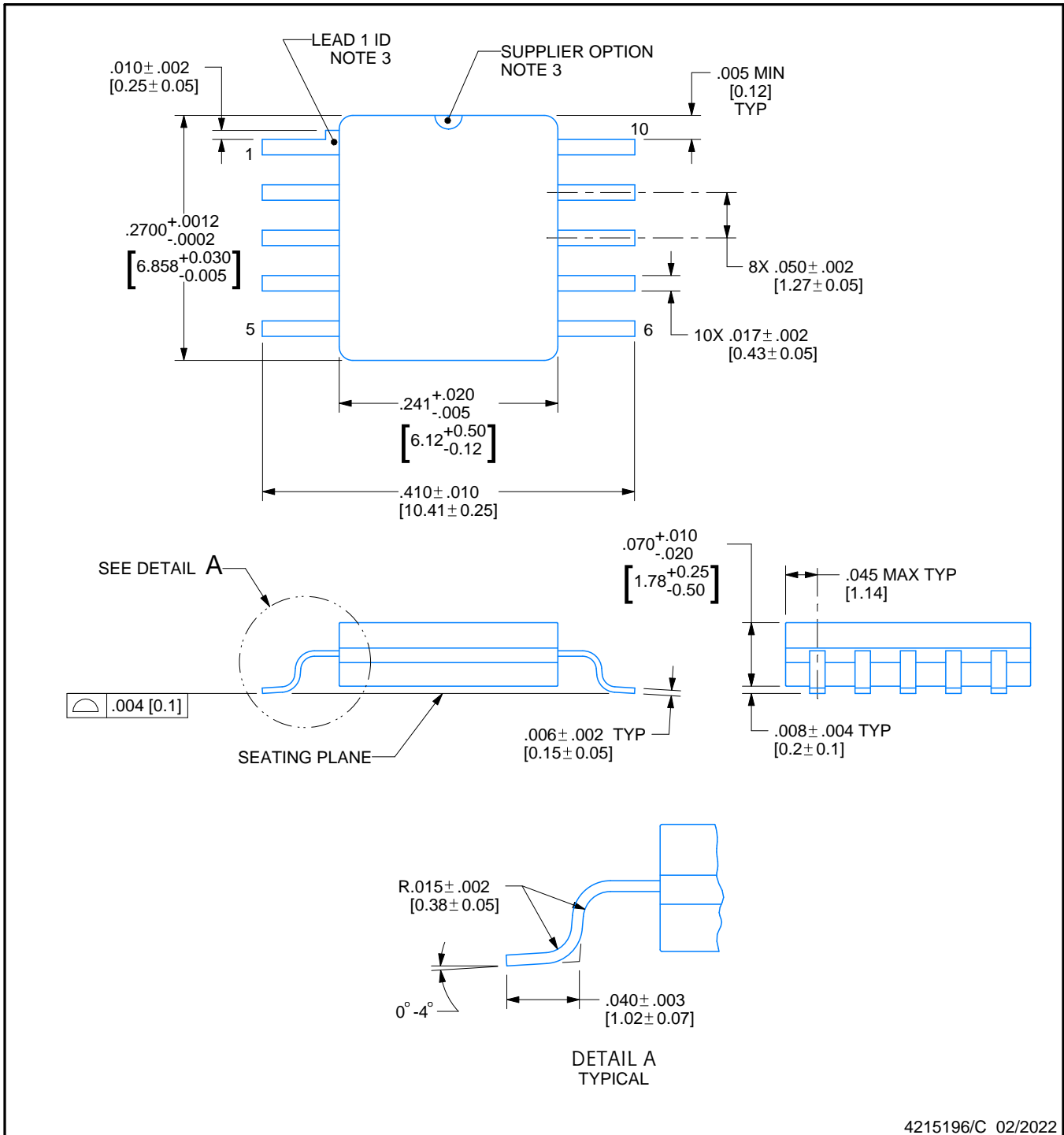


# PACKAGE OUTLINE

## NAC0010A

### CFP - 2.33mm max height

CERAMIC FLATPACK



#### NOTES:

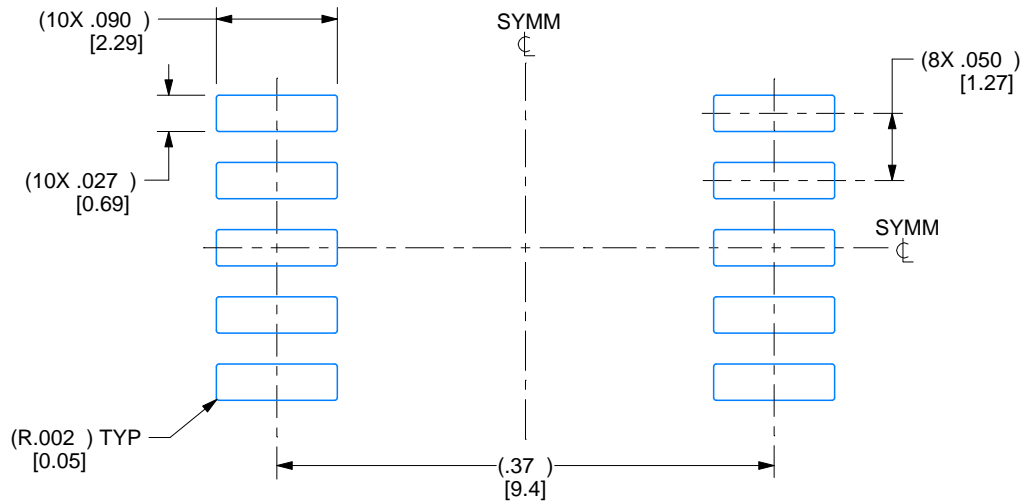
1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. For solder thickness and composition, see the "Lead Finish Composition/Thickness" link in the packaging section of the Texas Instruments website
3. Lead 1 identification shall be:
  - a) A notch or other mark within this area
  - b) A tab on lead 1, either side
4. No JEDEC registration as of December 2021

# EXAMPLE BOARD LAYOUT

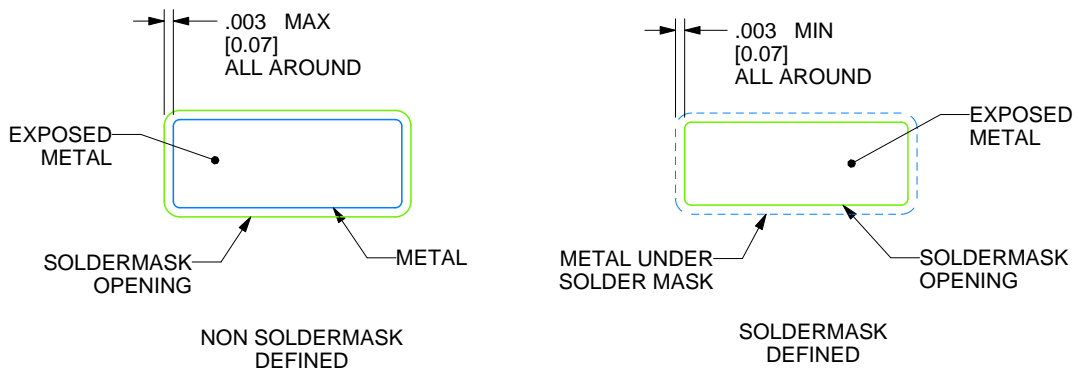
NAC0010A

CFP - 2.33mm max height

CERAMIC FLATPACK



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 7X



4215196/C 02/2022

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